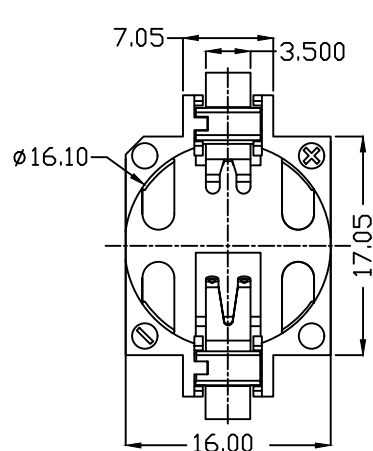


NOTE:

1.MATERIAL:

a.HOUSING:LCP UL94V-0

b.CONTACT:PHOSPHOR BRONZE

(SURFACE PLATING:AU 1u")

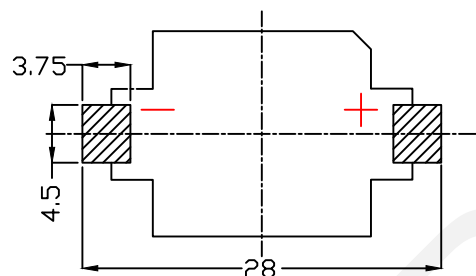
2.ELECTRIC:

a.CONTACT RESISTANCE:30 MILLIOHMS MAX

b.INSULATION RESISTANCE:1000 MEA OHMS MIN

c.DIELECTRIC VOLTAGE:500V AC ONE SEC LEVEL

d.OPERATING TEMPERATURE:-25°C~+85°C



PCB Layout Diagram
Top View

3	TERMINAL(-)	1	PHOSPHOR BRONZE,T=0.15mm	Au-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE,T=0.15mm	Au-Plating
1	HOUSING	1	LCP	WHITE
NO.	PART NAME	Q'TY	MATERIAL	PLATING &COLOR

RHTECP NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4		SCALE:---
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5

DRWN BY PAN

CHK'D BY FENG

APPR BY ZHAN

COIN CELL HOLDER SMD
CR1632 GOLD PLATED ROHS

THIRD ANGLE PROJECTION



RE-BH-CR1632-01-X-G0